Serial No. 09/905,172



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

David S. Mui et al.

Serial No.:

09/905,172

Filed:

07/13/2001

Title:

ETCH PATTERN DEFINITION USING A CVD ORGANIC LAYER AS AN

ANTI-REFLECTION COATING AND HARDMASK

Art Unit:

1765

Examiner:

Deo, Duy Vu Nguyen

Docket No.: 004227USA02/ETCH/SILICON

VIA FACSIMILE 703-872-9310 Mail Stop Fee Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## AMENDMENT AND RESPONSE

Sir:

Responsive to the Office Action mailed June 10, 2003 in the above matter, Applicants submit the following amendment and remarks.



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## Mayer, Fortkort & Williams, PC Attorneys At Law





□ Urge	mt	☐ For Review	☐ Please Comment	☐ Please Repl	y 🔲 Please Recycle
	David Bonham				
Re:	In connection with prosecution in Serial. No. 09/905,172, please find enclosed (a) an Amendment and Response and (b) a Terminal Disclaimer to Obviate a Double Patenting Rejection over a Prior Patent.			CCı	
Phone:				Date:	9/10/2003
Faoc:	703-	872-9310		Total pages:	: 11
Тог	Com	missioner for Paten	ts	From:	David Bonham (703) 433-0510

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